

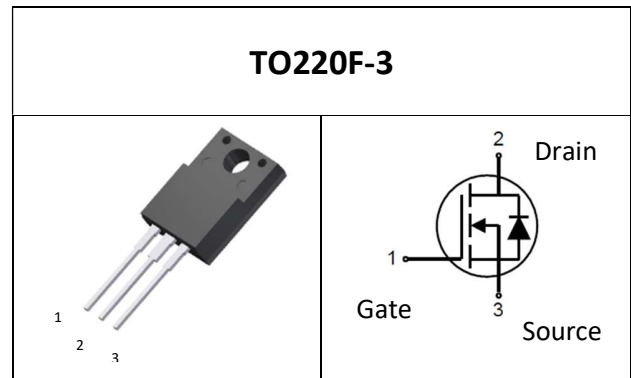
NW6520CW1-3

650V Silicon Carbide Mosfet

Parameter	Value	Unit
V_{RRM}	650	V
$R_{DS(on)}(V_{GS}=15V)$	200	$m\Omega$
$R_{DS(on)}(V_{GS}=18V)$	154	$m\Omega$
$I_F (T_C = 25^\circ C)$	15	A

Features

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low $R_{DS(on)}$
- Easy to Parallel
- Simple to Drive
- RoHS Compliant



Applications

- Power Factor Correction Modules
- Switch Mode Power Supplies
- DC-AC Inverters
- High Voltage DC/DC Converters

Description

The NW6520CW1-3 is a 650 V, SiC mosfet based on NovaWave's advanced SiC technology resulting in high performance and long-term reliability. It supports high-temperature operation while showing minimal losses , zero reverse recovery, and low leakage current.

Pin1-Gate

Pin2-Drain

Pin3-Source

Part Description

Part Number	Package	Marking
NW6520CW1-3	TO220F-3	NW6520CW1-3

Absolute Maximum Ratings

$T_J = 25^\circ\text{C}$ except as noted. Exceeding the maximum ratings may damage the device.

Parameter	Symbol	Value	Unit	Test conditions
Drain-Source Voltage	V_{DS}	650	V	
Continuous Drain Current	I_D	15 11	A	$T_C = 25^\circ\text{C}$ $V_{GS}=18\text{V}$ $T_C = 100^\circ\text{C}$
Peak Drain Current	I_{DM}	30	A	Pulse width t_p limited by T_{Jmax}
Power Dissipation	P_{tot}	48 24	W	$T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$
Operating Junction Range	T_J	-40 to +175	$^\circ\text{C}$	
Storage Temperature Range	T_{Stg}	-40 to +150	$^\circ\text{C}$	
Soldering Temperature	T_{sold}	260	$^\circ\text{C}$	1.6mm (0.063") from case for 10s
Gate-Source Voltage, max. Transient Voltage	V_{GSmax}	-8 to +22	V	$t_p \leq 0.5\mu\text{s}$, $D < 0.001$
Gate-Source Voltage	V_{GSmax}	-8 to +22	V	
Recommend Gate-Source Voltage	V_{GSop}	-4 to +18	V	

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Case	$R_{TH, J-C}$	3.147	$^\circ\text{C/W}$

Electrical Characteristics

Parameters	Symbol	Min	Typ	Max	Unit	Condition
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	650			V	$I_D=100\mu\text{A}$, $V_{GS}=0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}		1	10	μA	$V_{DS}=650\text{V}$, $V_{GS}=0\text{V}$
Gate-Source Leakage Current	I_{GSS}			250	nA	$V_{DS}=0\text{V}$, $V_{GS}=18\text{V}$

Gate Threshold Voltage	$V_{GS(th)}$	2	2.8 2.0	4	V	$V_{DS}=V_{GS}, I_D=2.5mA, T_J=25^{\circ}C$ $T_J=175^{\circ}C$
Drain-Source On-State Resistance	$R_{DS(on)}$		200 208	290	$m\Omega$	$V_{GS}=15V, I_D=10A, T_J=25^{\circ}C$ $T_J=175^{\circ}C$
			154 188	208	$m\Omega$	$V_{GS}=18V, I_D=10A, T_J=25^{\circ}C$ $T_J=175^{\circ}C$
Forward Transconductance	g_{fs}		7.2		S	$V_{DS}=20V, I_D=10A$
Input Capacitance	C_{iss}		308		pF	$V_{DS}=600V, f=1MHz, V_{GS}=0V$
Output Capacitance	C_{oss}		32		pF	
Reverse Transfer Capacitance	C_{rss}		4.2		pF	
C_{oss} Stored Energy	E_{oss}		5.3		pF	
Internal Gate Resistance	$R_{G(int)}$		3.9		Ω	$f=1MHz$
Total Gate Charge	Q_g		14		nC	$V_{DS}=400V, I_D=4.5A, V_{GS}=-4V/18V$
Gate to Source Charge	Q_{gs}		2.8		nC	
Gate to Drain Charge	Q_{gd}		6.4		nC	
Turn-On Delay Time	$t_{d(on)}$		6		ns	$V_{DD}=400V, I_D=4.5A,$ $V_{GS}=-4V/18V,$ $R_{G(ext)}=2.5\Omega,$ $L=200\mu H,$ $T_J=25^{\circ}C$
Rise Time	t_r		9		ns	
Turn-Off Delay Time	$t_{d(off)}$		8		ns	
Fall Time	t_f		11		ns	
Turn-On Energy	E_{on}		27		μJ	
Turn-Off Energy	E_{off}		6		μJ	

Reverse Diode Characteristics

Parameters	Symbol	Min	Typ	Max	Unit	Condition
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Diode Forward Voltage	V_{SD}		4.0 3.7		V	$V_{GS}=-4V, I_{SD}=5A, T_j=25^{\circ}C$ $T_j=175^{\circ}C$
Continuous Diode Forward Current	I_S		15 8		A	$V_{GS}=-4V, T_c=25^{\circ}C,$ $T_c=100^{\circ}C$
Reverse Recovery Time	t_{rr}		12		ns	$V_{GS}=-4V, I_{SD}=5A,$ $V_R=400V,$ $di/dt=1400A/\mu s,$ $T_j=25^{\circ}C$
Reverse Recovery Charge	Q_{rr}		62		nC	
Peak Reverse Recovery Current	I_{rrm}		5		A	

Electrical Performance Graphs

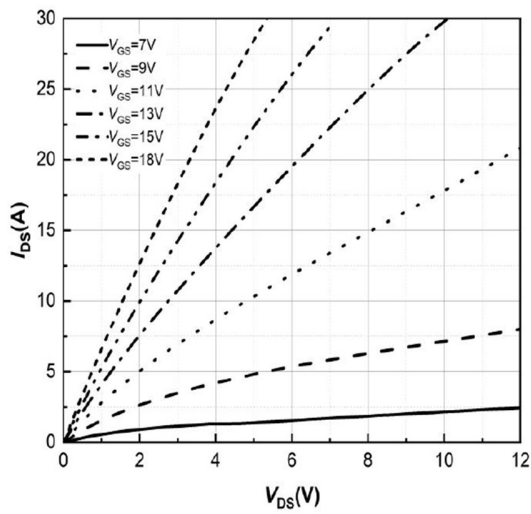


Figure 1: Output Characteristics
 $T_j=25^{\circ}C$

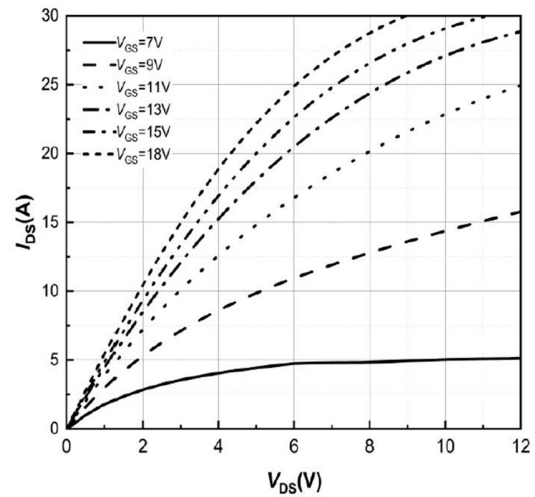


Figure 2: Output Characteristics
 $T_j=175^{\circ}C$

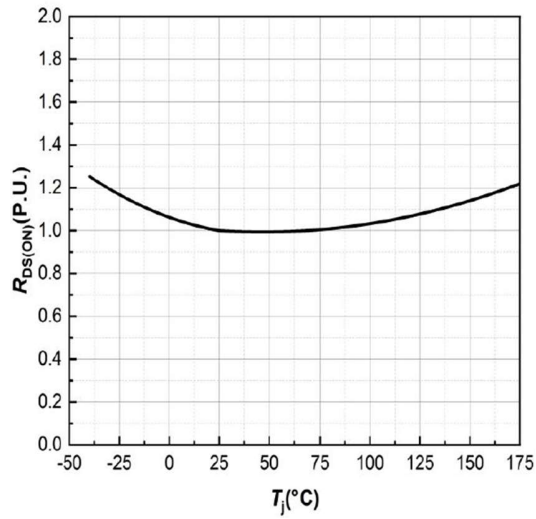


Figure 3: Normalized On-Resistance vs. Temperature

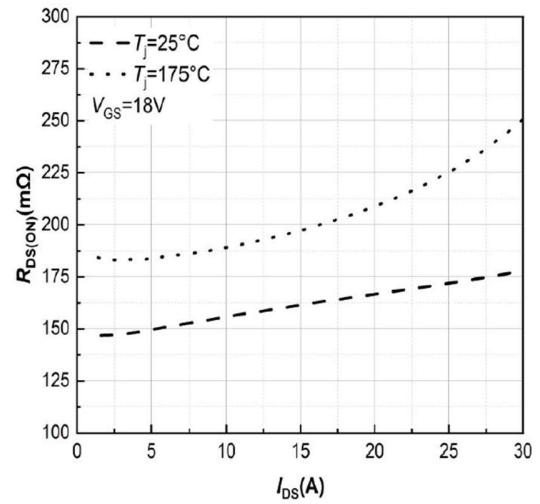


Figure 4: On-Resistance vs. Drain Current For Various Temperatures

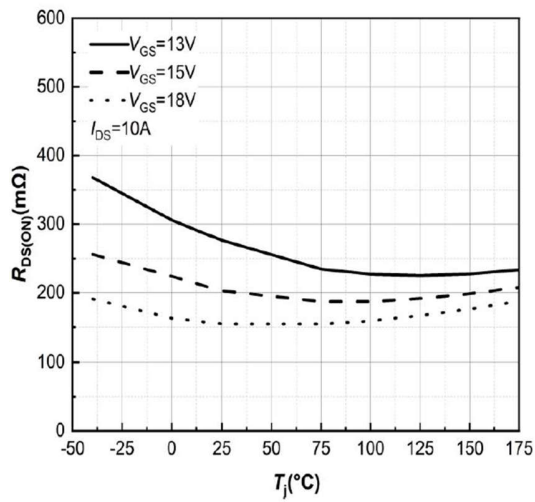


Figure 5: On-Resistance vs. Temperature For Various Gate Voltage

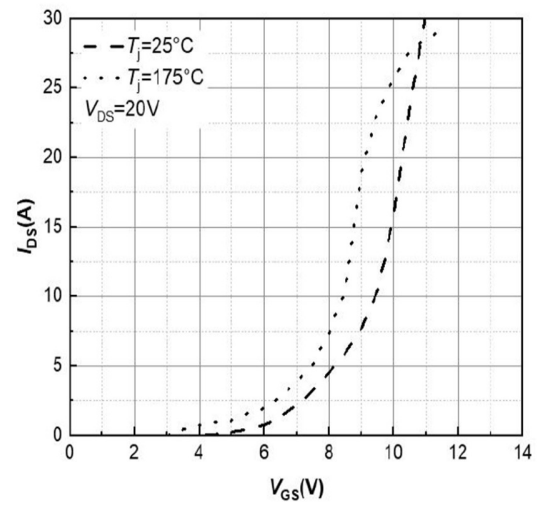


Figure 6: Transfer Characteristic for Various Junction Temperatures

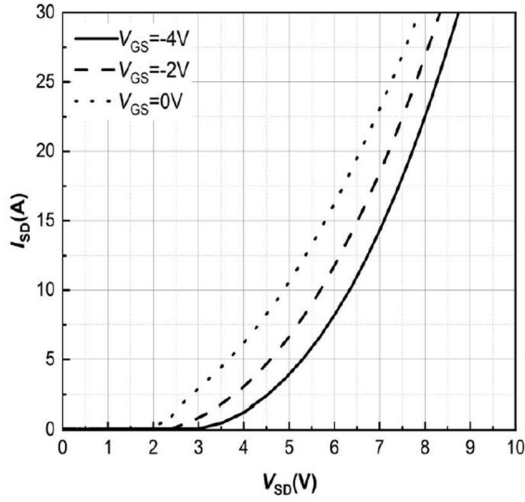


Figure 7: Body Diode Characteristic
 $T_j=25^{\circ}\text{C}$

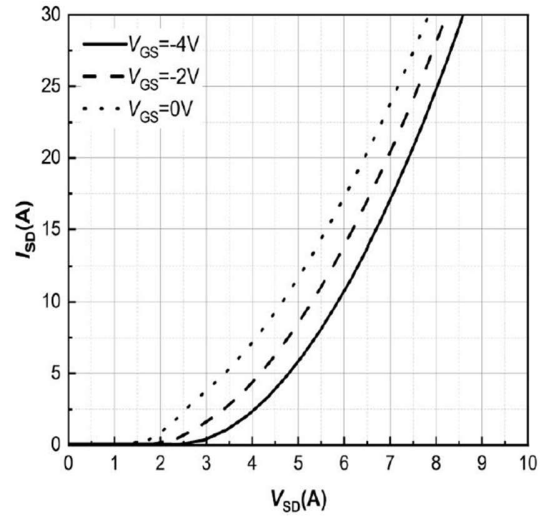


Figure 8: Body Diode Characteristic
 $T_j=175^{\circ}\text{C}$

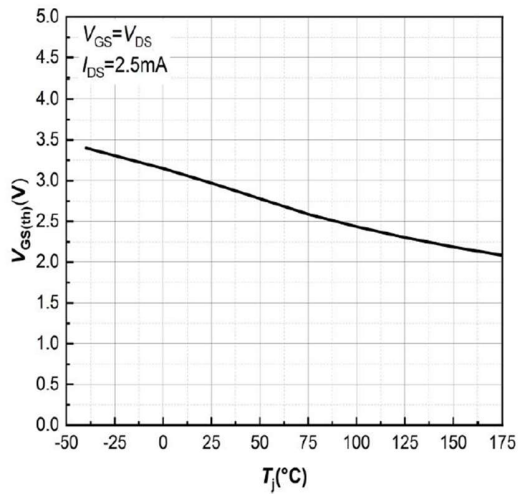


Figure 9. Threshold Voltage vs.
Temperature

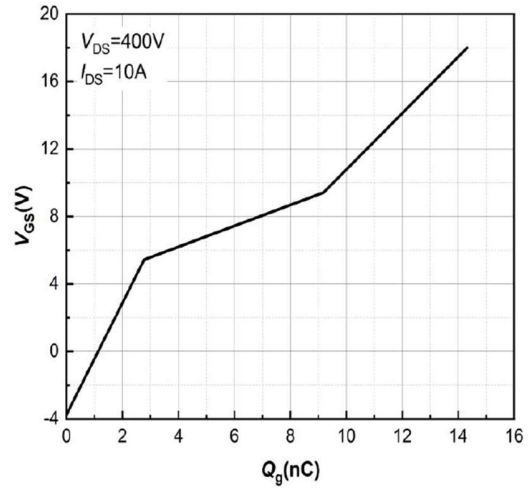


Figure 10. Gate Charge Characteristics

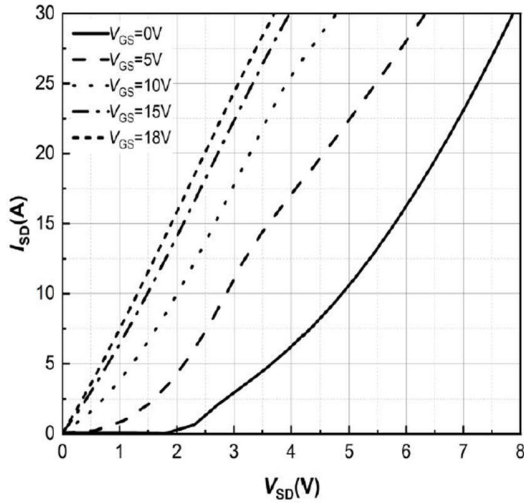


Figure 11. 3rd Quadrant Characteristic
 $T_j=25^{\circ}\text{C}$

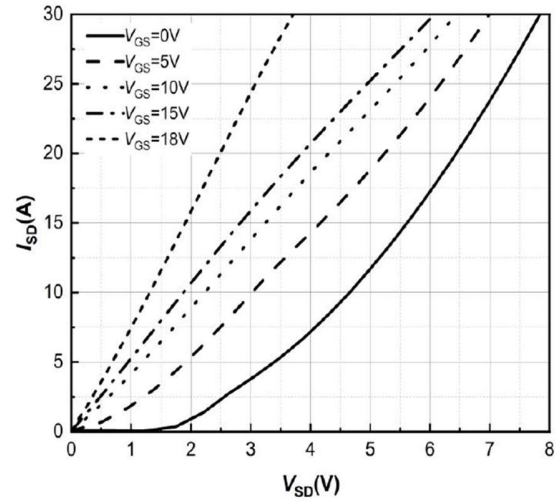


Figure 12. 3rd Quadrant Characteristic
 $T_j=175^{\circ}\text{C}$

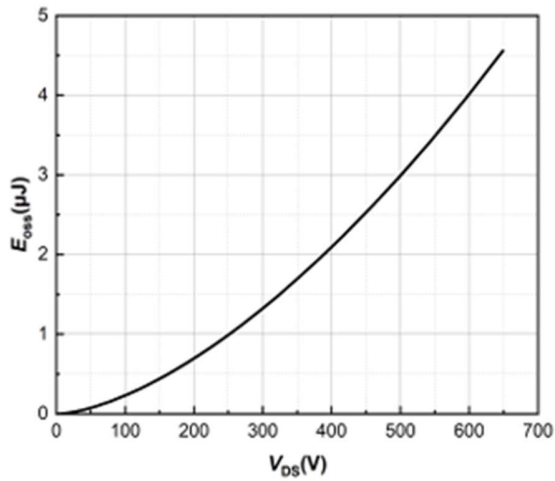


Figure 13: Output Capacitor Stored Energy

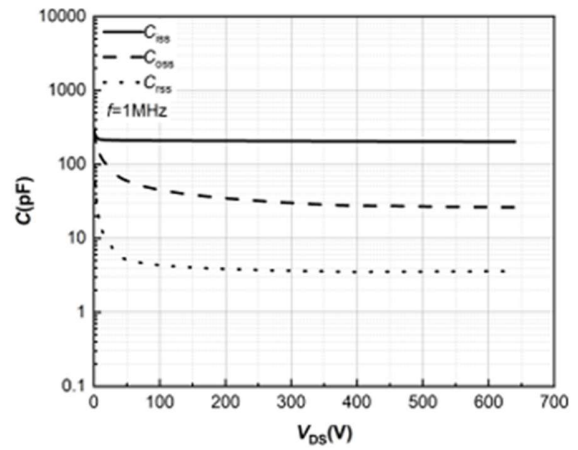


Figure 14: Capacitances vs. Drain-Source

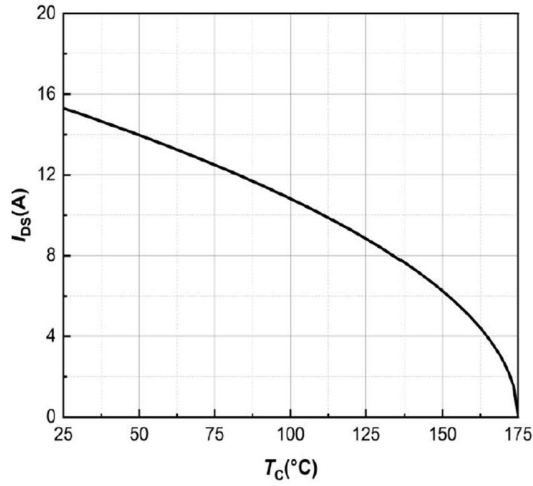


Figure 15: Continuous Drain Current Derating vs. Case Temperature

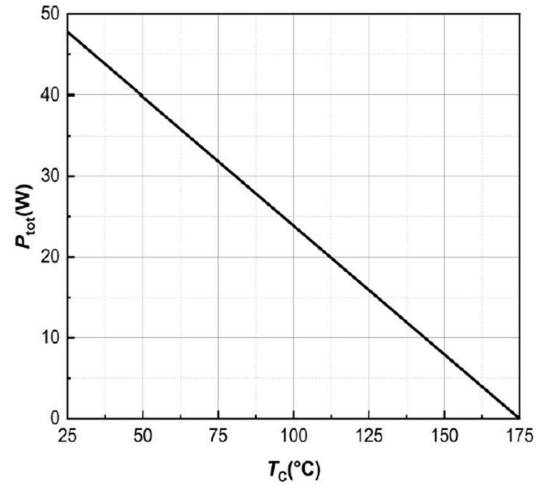


Figure 16: . Maximum Power Dissipation Derating vs. Case Temperature

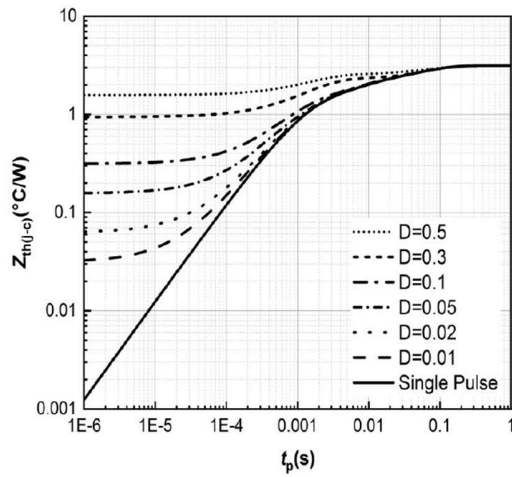


Figure 17: Transient Thermal Impedance

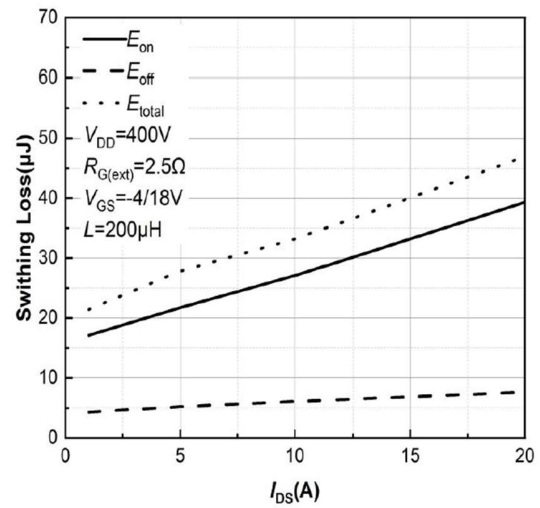


Figure 18: Clamped Inductive Switching Energy vs. Drain Current $T_j=25^\circ\text{C}$

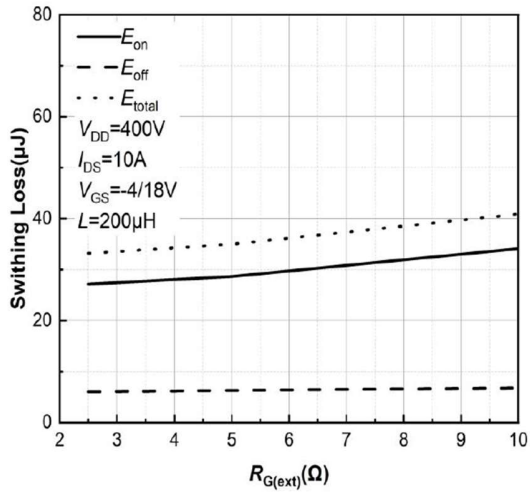


Figure 19: Clamped Inductive Switching Energy vs. $R_{G(\text{ext})}$ $T_J=25^\circ\text{C}$

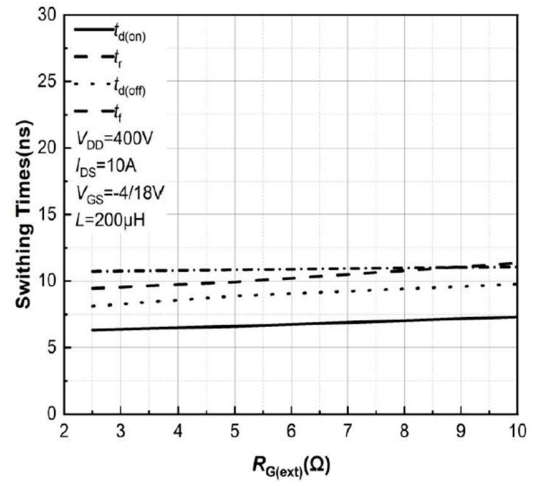


Figure 20: Switching Times vs. $R_{G(\text{ext})}$ $T_J=25^\circ$

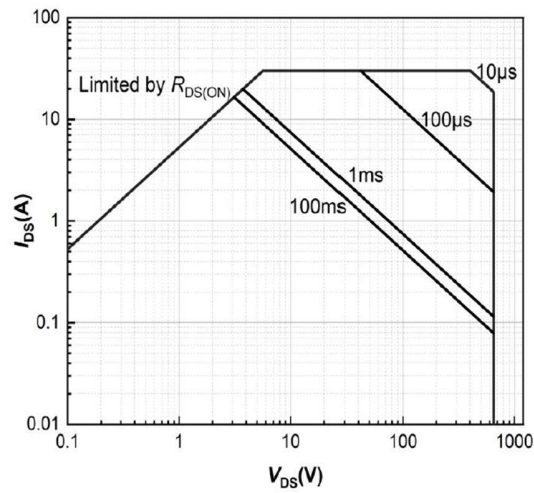
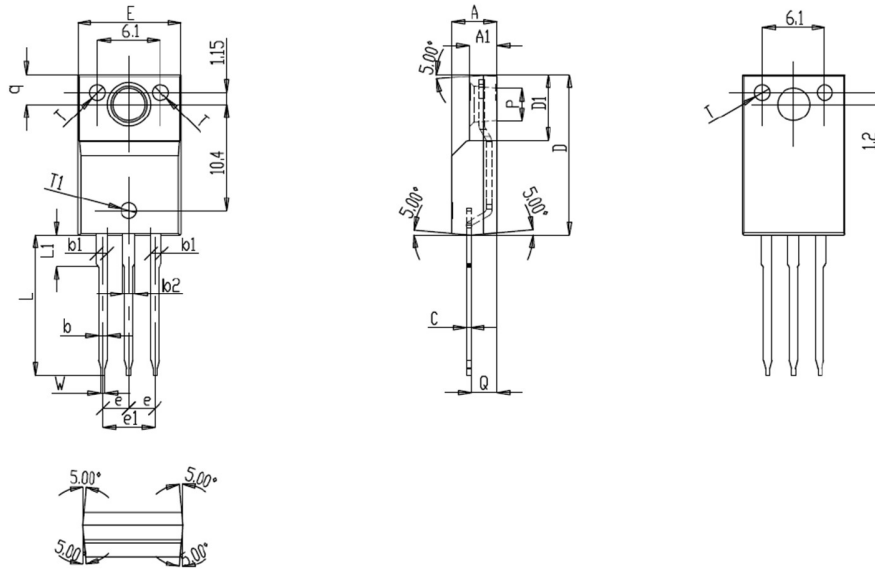


Figure 21: Safe Operating Area

Package Dimensions



SYMBOL	Unit(mm)		
	MIN	NOM	MAX
A	4.2	4.4	4.6
A1	2.5	2.7	2.9
b	0.7	0.8	0.9
b1	0.9	1.07	1.3
b2	1	1.17	1.4
C	0.4	0.5	0.6
D	15.4	15.63	15.8
D1	6	6.22	6.4
E	9.7	10.06	10.3
e	2.5	2.54	2.58
e1	5	5.08	5.12
L	13.5	13.9	14.4
L1	2.8	3.12	3.3
P	3	3.14	3.2
Q	2.3	2.44	2.6
q	2.6	2.86	3
W	0.3	0.37	0.5
T	1.3	1.52	1.7
T1	1.1	1.2	1.3

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